



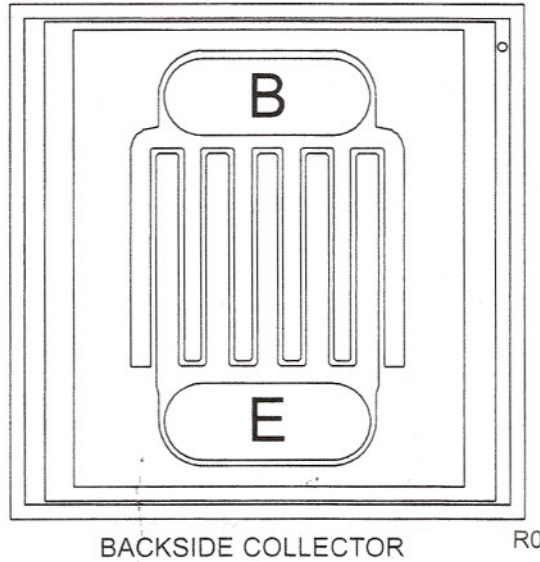
# Sierra Components, Inc.

924 Incline Way • Suite F • Incline Village, Nevada 89451  
 Phone: 775.831.1241 Fax: 775.831.3021

Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below.

2N3725A

### GEOMETRY



Process	EPITAXIAL PLANAR
Die Size	29 x 29 MILS
Die Thickness	7.1 MILS
Base Bonding Pad Area	11.8 x 4.5 MILS
Emitter Bonding Pad Area	11.8 x 4.5 MILS
Top Side Metalization	Al - 30,000Å
Back Side Metalization	Au-As - 13,000Å

**APPROVED BY:**  
**MFG: Central Semi**

DG 10.1.2  
 Rev A 3-4-99